



07/23/2012



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Docket No.: R106097US01

U.S. DEPARTMENT OF COMMERCE
Patent and Trademark Office

To the Director of the United States Patent and Trademark Office: Please record the attached documents or the new address(es) below.

1. Name of conveying party(ies):
Masayuki TERAJ

Additional names(s) of conveying party(ies) Yes No

3. Nature of conveyance/Execution Date(s):

Execution Date(s): June 14, 2012

- Assignment Merger
- Security Agreement Change of Name
- Joint Research Agreement
- Government Interest Assignment
- Executive Order 9424, Confirmatory License
- Other

2. Name and address of receiving party(ies):

Name: Renesas Electronics Corporation

Address: 1753, Shimonumabe, Nakahara-ku

City: Kawasaki-shi

State/Prov.: Kanagawa

Country: Japan

ZIP: _____

Additional name(s) & address(es) attached? Yes No

4. Application or patent numbers(s):

A. Patent Application No. (s)

13/551,511

This document is being filed together with a new application.

B. Patent No.(s)

7/18/12

Additional numbers attached? Yes No

5. Name and address to whom correspondence concerning document should be mailed:

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Registration No.: 34, 386

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6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 1.21(h) & 3.41) \$ 40.00

- Authorized to be charged by credit card
- Authorized to be charged to deposit account
- Enclosed
- None required (government interest not affecting title)

8. Payment Information

a. Credit Card Last 4 Numbers _____

Expiration Date _____

b. Deposit Account Number 50-0481 (deficiencies only)

Authorized User Name Sean M. McGinn

9. Signature:

Signature

Sean M. McGinn, Esq.

Name of Person Signing

07/23/2012 HTON11

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July 18, 2012

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Date

Total number of pages including cover sheet, attachments, and document:

ASSIGNMENT

(讓渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by Renesas Electronics Corporation, a corporation organized under the laws of Japan, located at 1753, Shimonumabe, Nakahara-ku, Kawasaki-shi, Kanagawa, Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said Renesas Electronics Corporation, its successors and assigns, all my right, title and interest, in and for the United States of America, in and to RESISTANCE CHANGE NONVOLATILE MEMORY DEVICE, SEMICONDUCTOR DEVICE, AND METHOD OF MANUFACTURING RESISTANCE CHANGE NONVOLATILE MEMORY DEVICE

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said Renesas Electronics Corporation, its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Renesas Electronics Corporation,

Signed on the date(s) indicated aside our signatures:

INVENTOR(S) (發明者フルネームサイン)		Date Signed (署名日)
1)	<u><i>Masayuki Terai</i></u> Masayuki TERAJ	<u>June 14, 2012</u>
2)	_____	_____
3)	_____	_____
4)	_____	_____
5)	_____	_____
6)	_____	_____
7)	_____	_____
8)	_____	_____
9)	_____	_____
10)	_____	_____